

## STACKED SEMICONDUCTOR DEVICE

### ABSTRACT OF THE DISCLOSURE

A stacked semiconductor device has a substrate having a conductor pattern and a die bonding portion. A first die is bonded on the die bonding portion of the  
5 substrate and is electrically connected to the conductor pattern via wires. A first adhesive layer provided on the substrate to cover the first die and the wires. The first adhesive layer has a greater top on which a second die is bonded. The second die is greater than the first die and is electrically connected to the pads of the conductor  
10 pattern via wires. A second adhesive layer provided on the substrate to cover the second die and the wires.